

**AMENDMENTS TO THE SPECIFICATION**

Paragraph on page 21, line 7 from the bottom to page 22, line 1:

The Cu conductive paste having the above composition was applied such that the thickness of the paste on the end surfaces 2a and 2b was 25  $\mu\text{m}$  after drying and the length  $[[\text{e}]] \text{ E}$  of electrode-covered portions in Fig. 1 was 50  $\mu\text{m}$ . Subsequently, the paste was baked in an oxygen atmosphere at an oxygen concentration of 0 to 5 ppm by keeping a maximum temperature of 850°C for ten minutes to form the first sintered electrode layers 7a and 8a.